FAIRCHILD SEMICONDUCTOR®

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FIN1101
LVDS Single Port High Speed Repeater

General Description

This single port repeater is designed for high speed interconnects utilizing Low Voltage Differential Signaling (LVDS) technology. It accepts and outputs LVDS levels with a typical differential output swing of 330 mV which provides low EMI at ultra low power dissipation even at high frequencies. It can directly accept multiple differential I/O including: LVPECL, HSTL, and SSTL-2 for translating directly to LVDS.

Features

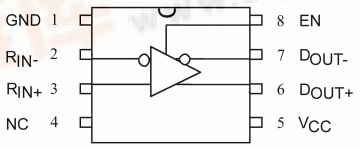
- Up to 1.6 Gb/s full differential path
- 3.5 ps max random jitter and 135 ps max deterministic jitter
- 3.3V power supply operation
- Wide rail-to-rail common mode range
- Ultra low power consumption
- LVDS receiver inputs accept LVPECL, HSTL, and SSTL-2 directly
- Power off protection
- 7 kV HBM ESD protection (all pins)
- Meets or exceed the TA/EIA-644-A LVDS standard
- Packaged in 8-pin SOIC and US8
- Open circuit fail safe protection

Ordering Code:

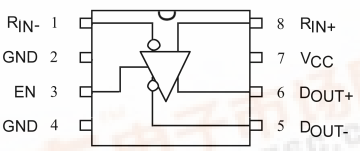
Order Number	Package Number	Package Description
FIN1101M	M08A	8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow [TUBE]
FIN1101MX	M08A	8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow [TAPE and REEL]
FIN1101K8X	MAB08A	8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide [TAPE and REEL]

Connection Diagrams

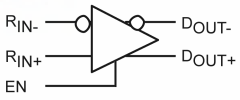
SOIC Package



US8 Package



Functional Diagram



Pin Descriptions

Pin Name	Description
R_{IN+}	Non-Inverting LVDS Inputs
R_{IN-}	Inverting LVDS Inputs
D_{OUT+}	Non-Inverting Driver Outputs
D_{OUT-}	Inverting Driver Outputs
EN	Driver Enable Pin
V_{CC}	Power Supply
GND	Ground

Function Table

Inputs			Outputs	
EN	R_{IN+}	R_{IN-}	D_{OUT+}	D_{OUT-}
H	H	L	H	L
H	L	H	L	H
H	Fail Safe Case		H	L
L	X	X	Z	Z

H = HIGH Logic Level L = LOW Logic Level
X = Don't Care Z = High Impedance

Absolute Maximum Ratings(Note 1)

Supply Voltage (V_{CC})	−0.5V to +4.6V
LVDS DC Input Voltage (V_{IN})	−0.5V to +4.6V
LVDS DC Output Voltage (V_{OUT})	−0.5V to +4.6V
Driver Short Circuit Current (I_{OSD})	Continuous 10 mA
Storage Temperature Range (T_{STG})	−65°C to +150°C
Max Junction Temperature (T_J)	150°C
Lead Temperature (T_L)	
(Soldering, 10 seconds)	260°C
ESD (Human Body Model)	7000V
ESD (Machine Model)	300V

Recommended Operating Conditions

Supply Voltage (V_{CC})	3.0V to 3.6V
Operating Temperature (T_A)	−40°C to +85°C
Magnitude of Input	
Differential Voltage ($\|V_{ID}\|$)	100 mV to V_{CC}
Common Mode Input Voltage	
(V_{IC})	(0V + $\|V_{ID}\|$/2) to (V_{CC} − $\|V_{ID}\|$/2)

Note 1: The "Absolute Maximum Ratings": are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature and output/input loading variables. Fairchild does not recommend operation of circuits outside databook specification.

DC Electrical Characteristics

Over supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Test Conditions		Min	Typ (Note 2)	Max	Units
V_{TH}	Differential Input Threshold HIGH	See Figure 1; V_{IC} = +0.05V, +1.2V, or (V_{CC} − 0.05V)				100	mV
V_{TL}	Differential Input Threshold LOW	See Figure 1; V_{IC} = +0.05V, +1.2V, or (V_{CC} − 0.05V)		−100			mV
V_{IH}	Input High Voltage (EN)			2.0		V_{CC}	V
V_{IL}	Input Low Voltage (EN)			GND		0.8	V
V_{OD}	Output Differential Voltage	R_L = 100 Ω, Driver Enabled, See Figure 2		250	330	450	mV
ΔV_{OD}	V_{OD} Magnitude Change from Differential LOW-to-HIGH					25	mV
V_{OS}	Offset Voltage			1.125	1.23	1.375	V
ΔV_{OS}	Offset Magnitude Change from Differential LOW-to-HIGH					25	mV
I_{OS}	Short Circuit Output Current	D_{OUT+} = 0V & D_{OUT-} = 0V, Driver Enabled			−3.4	−6	mA
		V_{OD} = 0V, Driver Enabled			±3.4	±6	mA
I_{IN}	Input Current (EN, D_{INX+}, D_{INX-})	V_{IN} = 0V to V_{CC}, Other Input = V_{CC} or 0V (for Differential Inputs)				±20	µA
I_{OFF}	Power-Off Input or Output Current	V_{CC} = 0V, V_{IN} or V_{OUT} = 0V to 3.6V				±20	µA
I_{CCZ}	Disabled Power Supply Current	Drivers Disabled			3.2	5.5	mA
I_{CC}	Power Supply Current	Drivers Enabled, Any Valid Input Condition			9.3	13.5	mA
I_{OZ}	Disabled Output Leakage Current	Driver Disabled, D_{OUT+} = 0V to 3.6V or D_{OUT-} = 0V to 3.6V				±20	µA
V_{IC}	Common Mode Voltage Range	$\|V_{ID}\|$ = 100 mV to V_{CC}		0V + $\|V_{ID}\|$/2		V_{CC}− ($\|V_{ID}\|$/2)	V
C_{IN}	Input Capacitance		EN Input		2.2		pF
			Data Input		2.0		
C_{OUT}	Output Capacitance				2.6		pF

Note 2: All typical values are at T_A = 25°C and with V_{CC} = 3.3V.

AC Electrical Characteristics

Over supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ (Note 3)	Max	Units
t_{PLHD}	Differential Propagation Delay LOW-to-HIGH	R_L = 100 Ω, C_L = 5 pF, V_{ID} = 200 mV to 450 mV, V_{IC} = $\|V_{ID}\|/2$ to (V_{CC}– (V_{ID}/2), Duty Cycle = 50%, See Figure 3 and Figure 4	0.75	1.1	1.75	ns
t_{PHLD}	Differential Propagation Delay HIGH-to-LOW		0.75	1.1	1.75	ns
t_{TLHD}	Differential Output Rise Time (20% to 80%)		0.29	0.40	0.58	ns
t_{THLD}	Differential Output Fall Time (80% to 20%)		0.29	0.40	0.58	ns
$t_{SK(P)}$	Pulse Skew $\|t_{PLH} - t_{PHL}\|$			0.01	0.2	ns
$t_{SK(PP)}$	Part-to-Part Skew (Note 4)				0.5	ns
f_{MAX}	Maximum Frequency (Note 5)(Note 6)		400	800		MHz
t_{PZHD}	Differential Output Enable Time from Z to HIGH	R_L = 100 Ω, C_L = 5 pF, See Figure 2 and Figure 3		2.1	5	ns
t_{PZLD}	Differential Output Enable Time from Z to LOW			2.3	5	ns
t_{PHZD}	Differential Output Disable Time from HIGH to Z			1.5	5	ns
t_{PLZD}	Differential Output Disable Time from LOW to Z			1.8	5	ns
t_{DJ}	LVDS Data Jitter, Deterministic	V_{ID} = 300 mV, PRBS = 2^{23} – 1, V_{IC} = 1.2V at 800 Mbps		85	135	ps
t_{RJ}	LVDS Clock Jitter, Random (RMS)	V_{ID} = 300 mV V_{IC} = 1.2 V at 400 MHz		2.1	3.5	ps

Note 3: All typical values are at T_A = 25°C and with V_{CC} = 3.3V, V_{ID} = 300mV, V_{IC} = 1.2V unless otherwise specified.

Note 4: $t_{SK(PP)}$ is the magnitude of the difference in differential propagation delay times between identical channels of two devices switching in the same direction (either LOW-to-HIGH or HIGH-to-LOW) when both devices operate with the same supply voltage, same temperature, and have identical test circuits.

Note 5: Passing criteria for maximum frequency is the output V_{OD} > 200 mV and the duty cycle is 45% to 55% with all channels switching.

Note 6: Output loading is transmission line environment only; C_L is < 1 pF of stray test fixture capacitance.

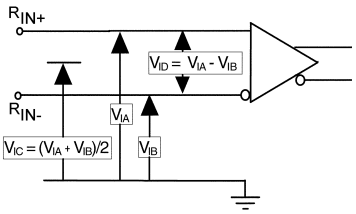


FIGURE 1. Differential Receiver Voltage Definitions and Propagation I and Transition Time Test Circuit

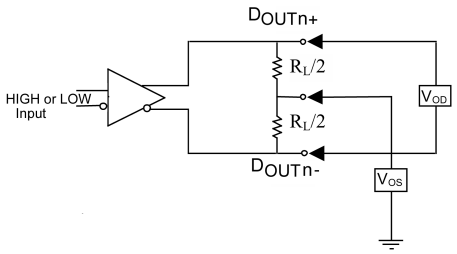
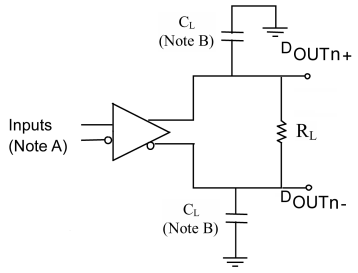


FIGURE 2. Differential Driver DC Test Circuit



Note A: All LVDS input pulses have frequency = 10MHz, t_R or t_F < = 0.5 ns

Note B: C_L includes all probe and test fixture capacitances

FIGURE 3. Differential Driver Propagation Delay and Transition Time Test Circuit

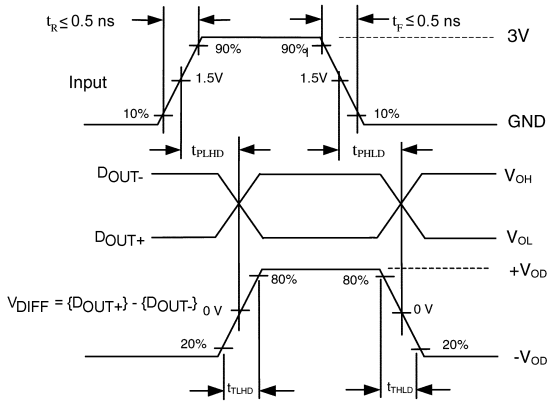
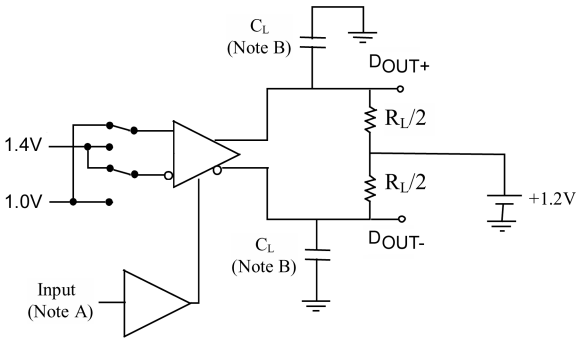


FIGURE 4. AC Waveforms



Note A: All LVTTL input pulses have frequency = 10 MHz, t_R or t_F < = 2 ns
Note B: C_L includes all probe and test fixture capacitances

FIGURE 5. Differential Driver Enable and Disable Test Circuit

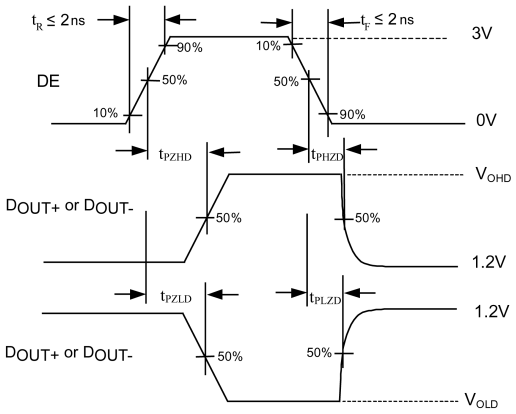
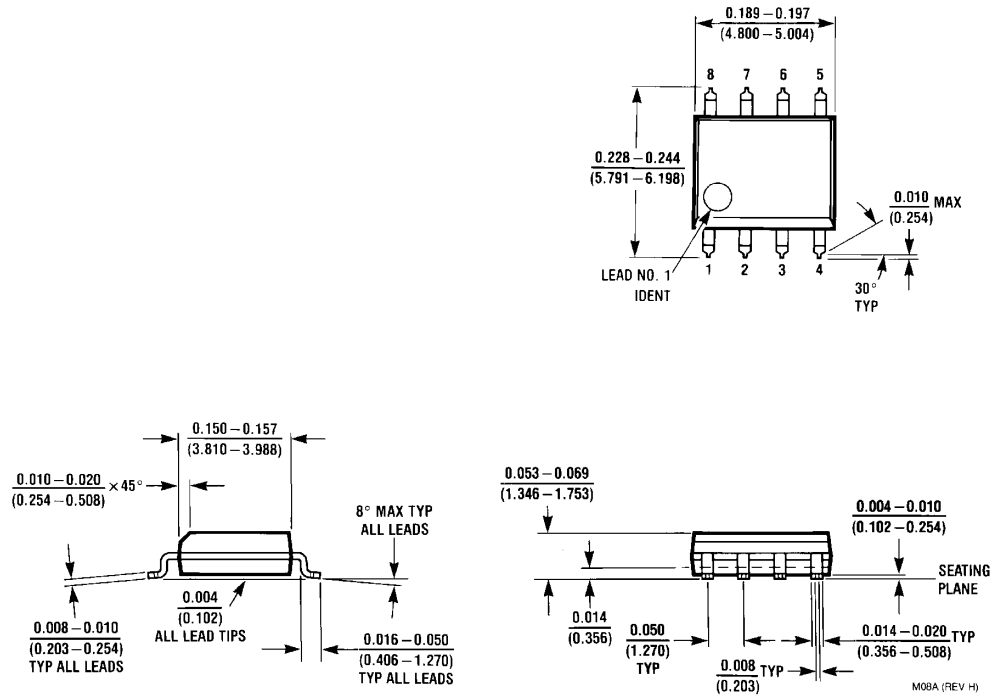


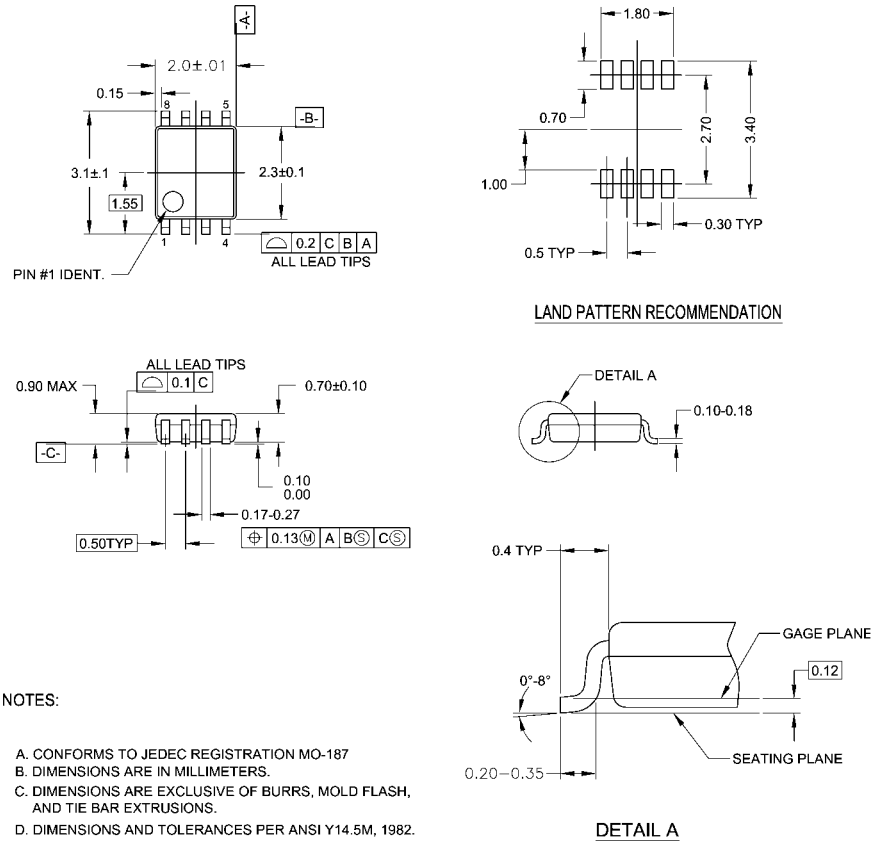
FIGURE 6. Enable and Disable AC Waveforms

Physical Dimensions inches (millimeters) unless otherwise noted



8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
Package Number M08A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-187
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MAB08AREVC

8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide
Package Number MAB08A

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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